

ABSTRACT

An object of the present invention is to provide a photoresist stripping composition which exhibits high stripping performance even for a cured resist, shows little decrease in stripping performance when water evaporates even with a composition containing a small amount of water, and can prevent corrosion of a substrate-forming metal, such as Cu, Al, or Si, that comes in contact with a liquid. The object was achieved by a photoresist stripping composition, the composition containing a quaternary ammonium hydroxide (A), a sugar alcohol (B), an amine (C), water (D), DMSO (E), and ethylene glycol (F), wherein a content of water (D) is 1.0 to 10 mass% with respect to a total mass of the composition.

No Figure